

D425-VB Datasheet

P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|------------------------------------|---------------------------------|-----------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^d | Q _g (Typ.) | | |
| - 30 | 0.018 at V _{GS} = - 10 V | - 40 | 13 nC | | |
| - 30 | 0.025 at V _{GS} = - 4.5 V | - 35 | 13110 | | |

FEATURES

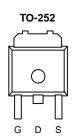
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g Tested

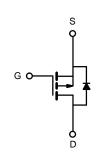
Pb-free RoHS



APPLICATIONS

- Load Switch
- · Battery Switch





P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS $T_A =$ | = 25 °C, unless other | erwise noted | | |
|----------------------------------------------------|-----------------------------------|----------------|------------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | - 30 | V | |
| Gate-Source Voltage | V _{GS} | ± 20 | V | |
| | T _C = 25 °C | | - 40 | |
| Continuous Proin Current (T. – 150 °C) | T _C = 70 °C | 1 , [| - 35 | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | l _D | - 30.0 ^{a, b} | |
| | T _A = 70 °C | | - 28 ^{a, b} | Α |
| Pulsed Drain Current | I _{DM} | - 150 | | |
| Continuous Courses Brain Binds Coursest | T _C = 25 °C | | - 3.5 | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | ls – | - 2.1 ^{a, b} | |
| | T _C = 25 °C | | 40 | |
| Maximum Davier Dissipation | T _C = 70 °C | | 27 | W |
| Maximum Power Dissipation | T _A = 25 °C | P _D | 2.5 ^{a, b} | VV |
| | T _A = 70 °C | | 1.6 ^{a, b} | |
| Operating Junction and Storage Temperature Range | T _J , T _{sta} | - 55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---------------------------------------------|--------------|-------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^{a, c} | t ≤ 10 s | R _{thJA} | 40 | 50 | °C/W | |
| Maximum Junction-to-Foot | Steady State | R _{thJF} | 24 | 30 | C/VV | |

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on $T_C = 25$ °C.



| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|-----------------------------------------------|-------------------------|----------------------------------------------------------------------------------------------|-------|--------|-------|--------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ | - 30 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = - 250 μA | | - 31 | | mV/°C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | η = - 250 μΑ | | 4.5 | | mv/°C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 1.0 | | - 2.5 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| Zara Cata Valtaga Drain Current | I | V _{DS} = - 30 V, V _{GS} = 0 V | | | - 1 | ^ | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C | | | - 5 | - 5 μA | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$ | - 40 | | | Α | |
| | D | V _{GS} = - 10 V, I _D = - 7.0 A | | 0.018 | | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 5.6 A | | 0.025 | | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 7.0 A | | 18 | | S | |
| Dynamic ^b | | · | | | | | |
| Input Capacitance | C _{iss} | | | 1455 | | pF | |
| Output Capacitance | C _{oss} | $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 180 | | | |
| Reverse Transfer Capacitance | C _{rss} | | | 145 | | | |
| Tatal Oata Obarra | | $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$ | | 25 | 38 | | |
| Total Gate Charge | Q _g | | 13 | 20 | 1 | | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$ | | 3.5 | | nC | |
| Gate-Drain Charge | Q _{qd} | | | 5.5 | | 1 | |
| Gate Resistance | R _q | f = 1 MHz | 0.4 | 2.0 | 4.0 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 10 | 20 | | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_L = 2.7 \Omega$ | | 13 | 20 | | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$ | | 23 | 35 | | |
| Fall Time | t _f | 1 | | 9 | 18 | 1 | |
| Turn-On Delay Time | t _{d(on)} | | | 38 | 57 | ns | |
| Rise Time | t _r | $V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$ | | 89 | 134 | 1 | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \simeq -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$ | | 22 | 33 | 1 | |
| Fall Time | t _f | 1 | | 11 | 17 | 1 | |
| Drain-Source Body Diode Characteris | tics | | | | | | |
| Continous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 6.5 | | |
| Pulse Diode Forward Current | I _{SM} | | | | - 30 | A | |
| Body Diode Voltage | V _{SD} | I _S = - 5.6 A, V _{GS} = 0 V | | - 0.71 | - 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 22 | 33 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 17 | 26 | nC | |
| Reverse Recovery Fall Time | t _a | $I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | | 13 | | ns | |
| Reverse Recovery Rise Time | t _b | 1 | | 9 | | | |

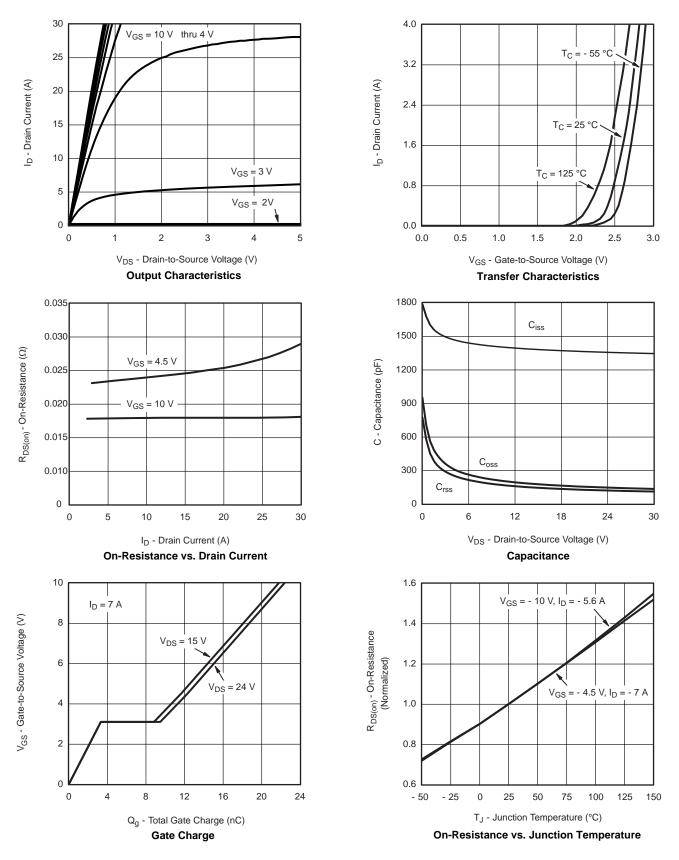
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

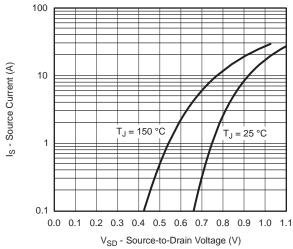
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

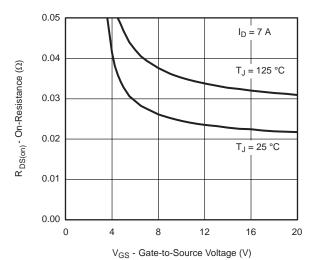




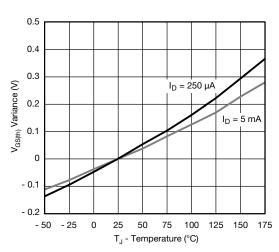




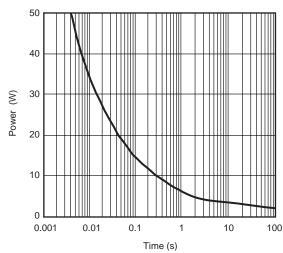
Source-Drain Diode Forward Voltage



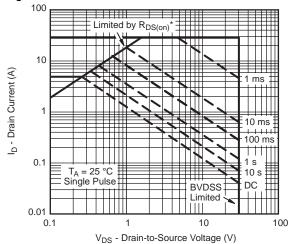
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



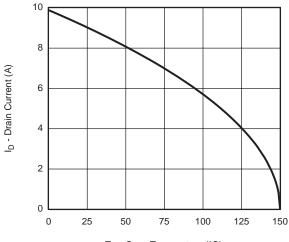
Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

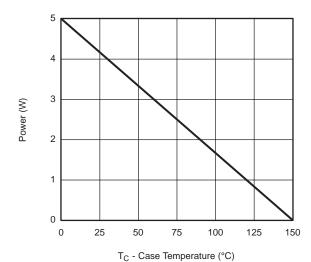
Safe Operating Area



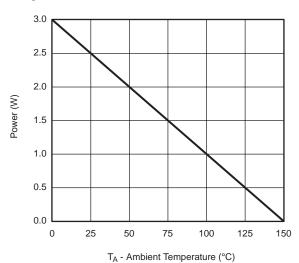


T_C - Case Temperature (°C)

Current Derating*



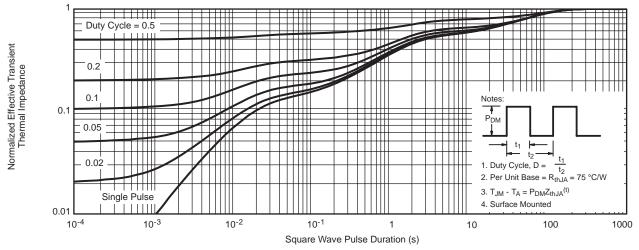
Power, Junction-to-Foot



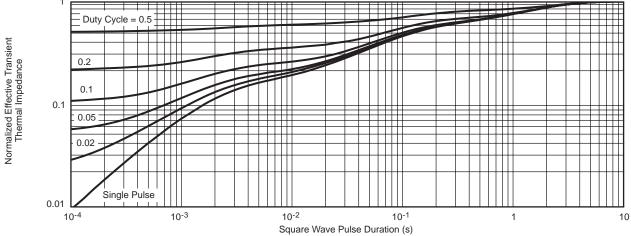
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





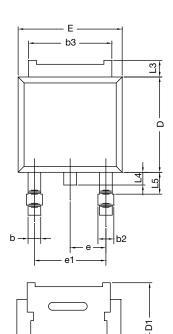
Normalized Thermal Transient Impedance, Junction-to-Ambient



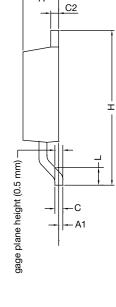
Normalized Thermal Transient Impedance, Junction-to-Foot



TO-252AA CASE OUTLINE



E1



| | MILLIN | METERS | INCHES | | | |
|---------------------------------|----------|--------|--------|-------|--|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | | |
| Α | 2.18 | 2.38 | 0.086 | 0.094 | | |
| A1 | - | 0.127 | - | 0.005 | | |
| b | 0.64 | 0.88 | 0.025 | 0.035 | | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | | |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 | | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | | |
| D1 | 5.21 | - | 0.205 | - | | |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | | |
| E1 | 4.32 | - | 0.170 | - | | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | | |
| е | 2.28 BSC | | 0.090 | BSC | | |
| e1 | 4.56 BSC | | 0.180 | BSC | | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | | |
| L4 | - | 1.02 | - | 0.040 | | |
| L5 | 1.14 | 1.52 | 0.045 | 0.060 | | |
| ECN: Y12-0247-Rev. M. 24-Dec-12 | | | | | | |

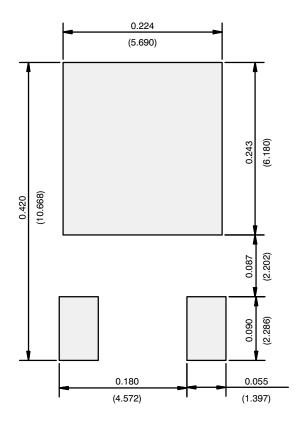
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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